

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

NOTE:

1. MATERIAL:

- 1.1 INSULATOR:LCP UL 94V-0
- 1.2 CONTACT:BRONZE(T=0.20mm)
- 1.3 SHELL:SUS201(T=0.30mm)

2. ELECTRICAL CHARACTERISTICS:

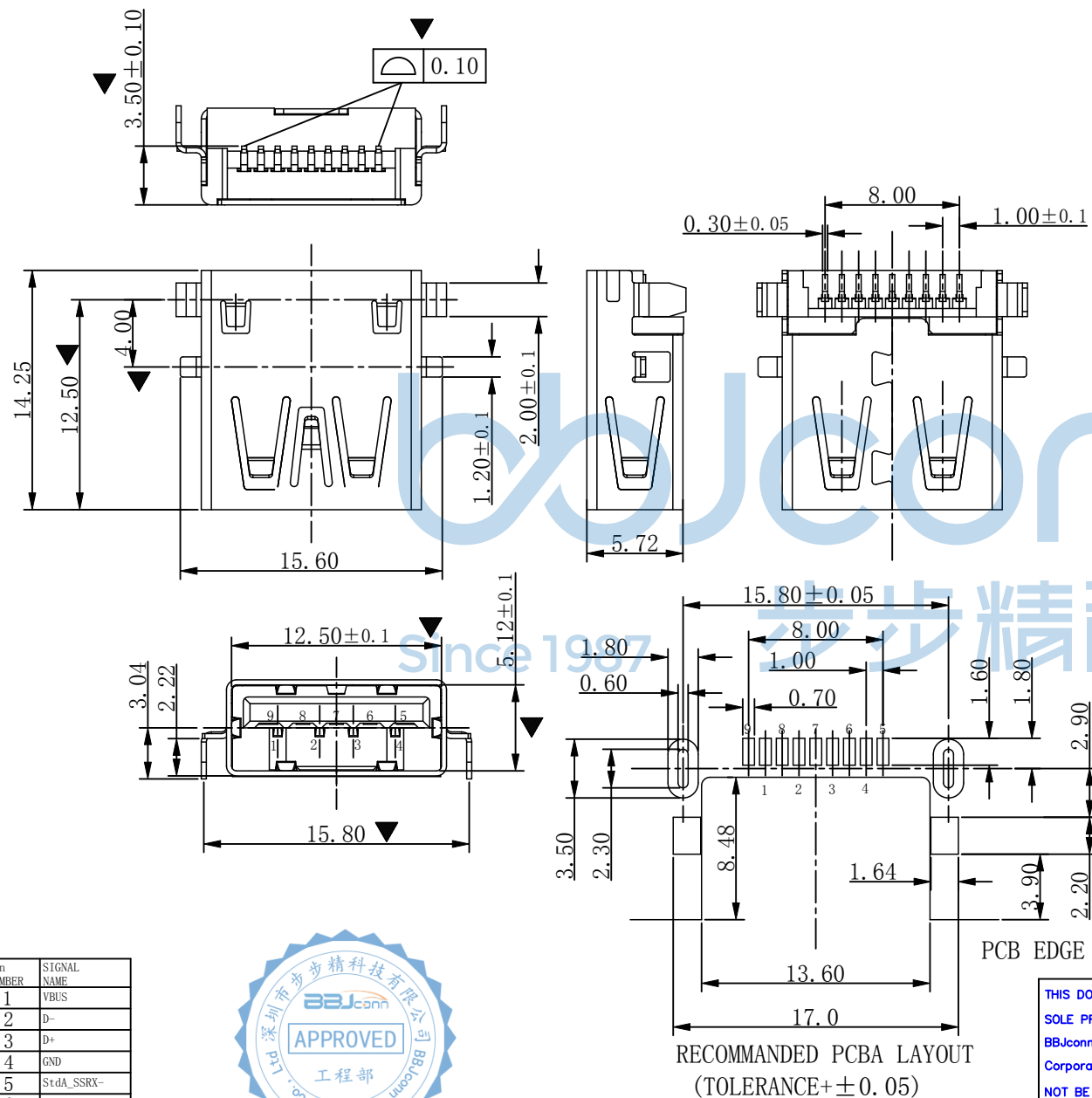
- 2.1 CONTACT RESISTANCE:30mΩ MAXIMUM
- 2.2 CONTACT CURRENT RATING:1.5A
- 2.3 DIELECTRIC WITHSTANDING VOLTAGE:500 V R. M. S.
- 2.4 INSULATION RESISTANCE 1000 MEGOHMS MIN
- 2.5 OPERATING TEMPERATURE:-40° C ~ 85° C

3. MECHANICAL CHARACTERISTICS:

- 3.1 MATING FORCE:3.57kg MAX
- 3.2 UNMATED FORCE:1.02kg MIN
- 3.3 DURABILITY:MANDATORY:5,000 CYCLES

4. PLATING

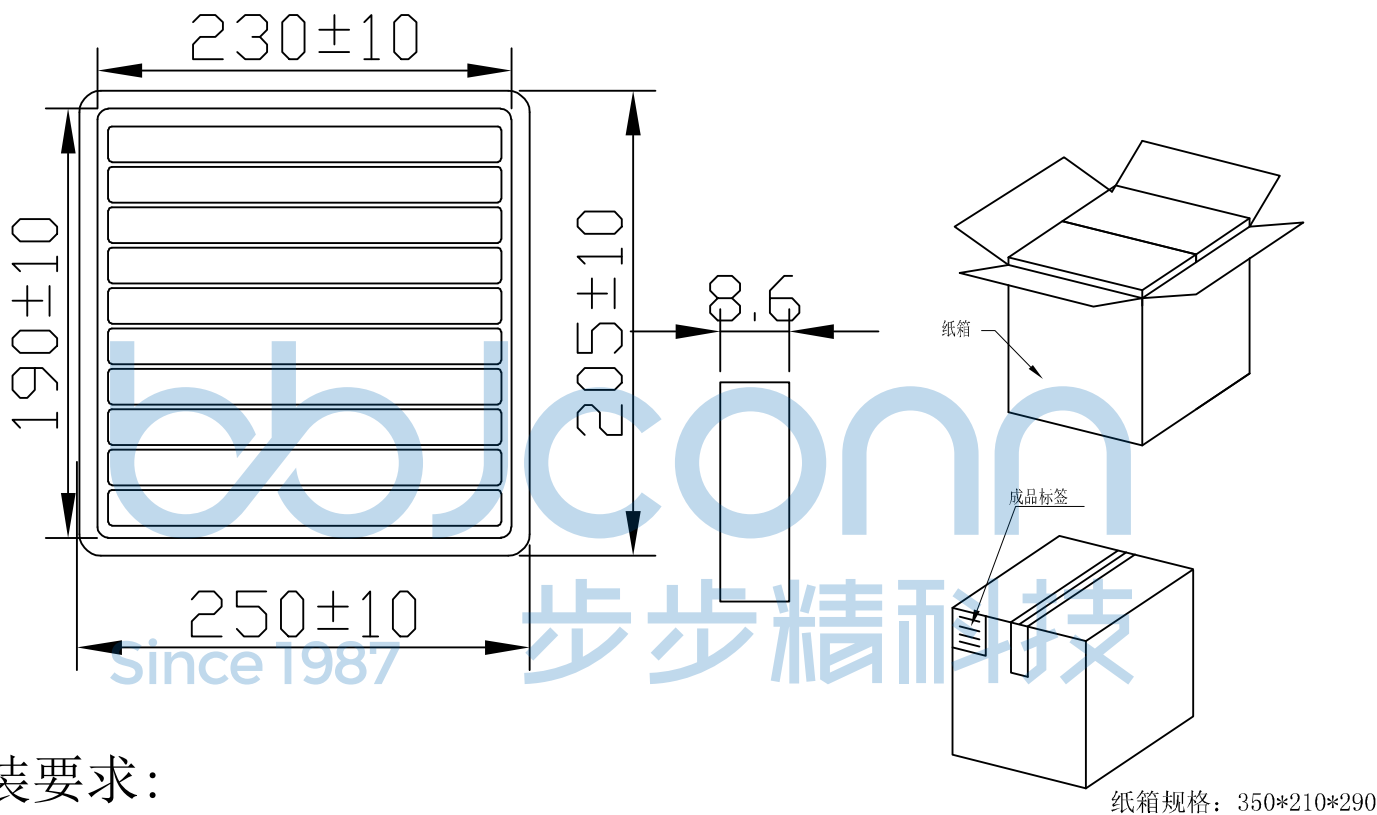
- 4.1 TERMINAL:
50u" MIN NICKEL ALL OVER
100u"MIN Tin ON SOLDER AREA
(1~30)u"Au ON CONTACT AREA
- 4.2 SHELL:100u"MIN. NICEL ALL OVER
- 5."▼" FOR MAJOR DIM



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

RECOMMENDED PCBA LAYOUT
(TOLERANCE+±0.05)

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PDWG.NO: 0471-1		PJ. NO.: 127-271-090011-Y4G SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2			



1. 包装要求:
- 1.1 每盒吸塑盒包装100pcs;
 - 1.2 每20盘放一箱, 共计2000PCS;
 - 1.3 纸箱外贴上标签。

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APPD.	JM_Zheng	PJ. NO.: 127-271-090011-Y4G		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG.NO:	0471-1	DR.	TSP	SCALE: N/A	REV.: A0
				UNIT: mm	PAGE: 2/2